

# Silicon 3D detectors irradiated with pions and protons



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*of*  
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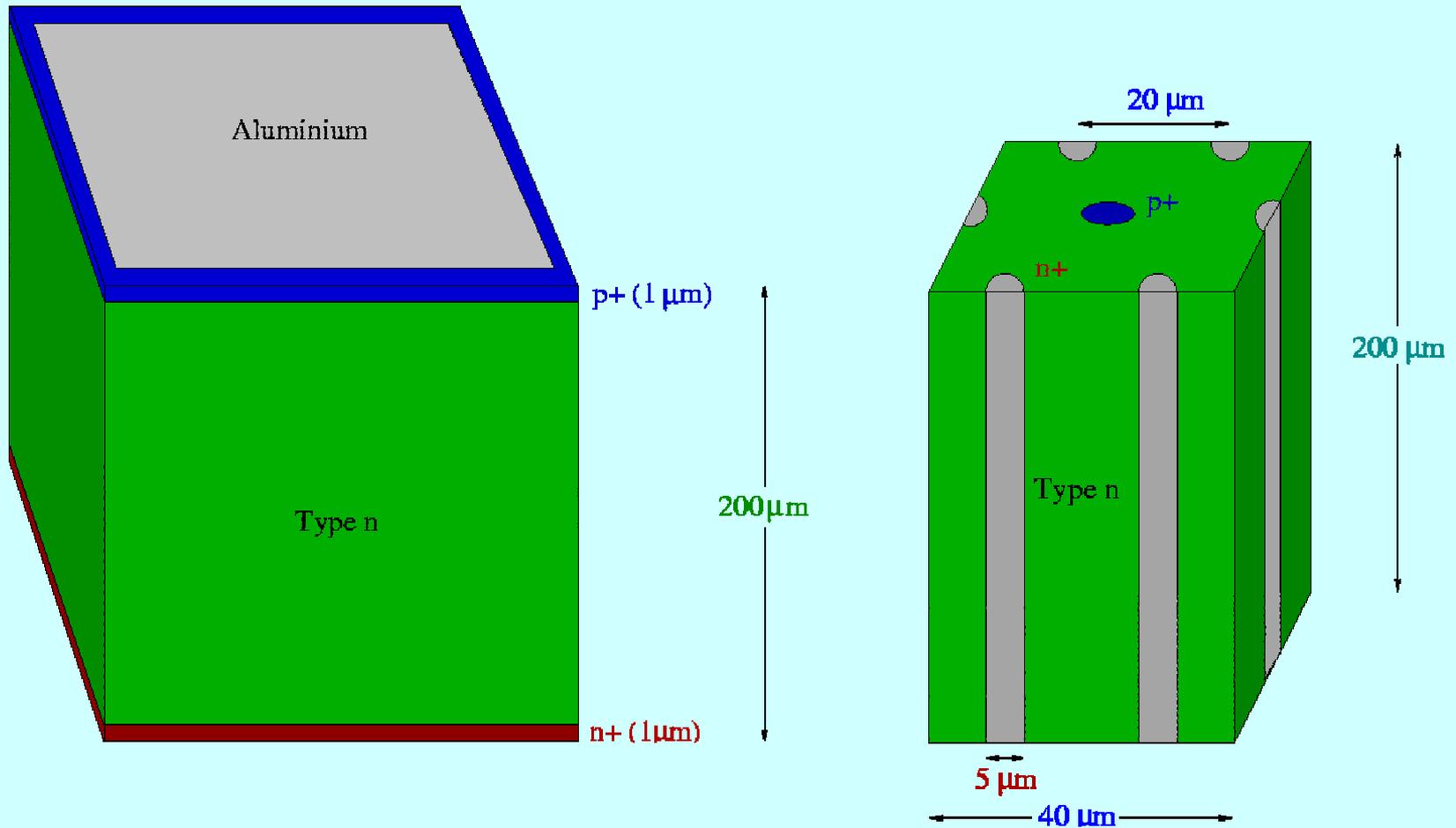
G. Pellegrini, V. Wright, R. Bates, L. Haddad,  
J. Melone, V. O'Shea, K.M. Smith, M. Rahman

# Overview



- **Introduction**
- **Results from irradiation:**
  - Pions**
  - Protons**
- **What is next?**
- **Conclusion**

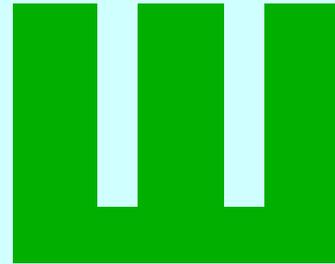
# Introduction



# Fabrication steps

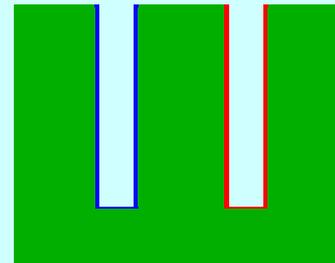


● **Creation of the vias**



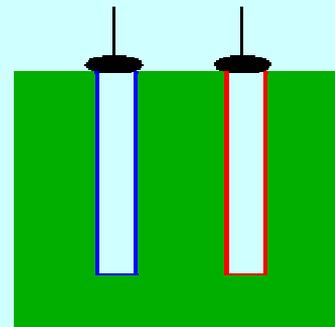
**Dry etching**  
**Laser drilling**  
**PEC etching**

● **Creation of the electrodes**



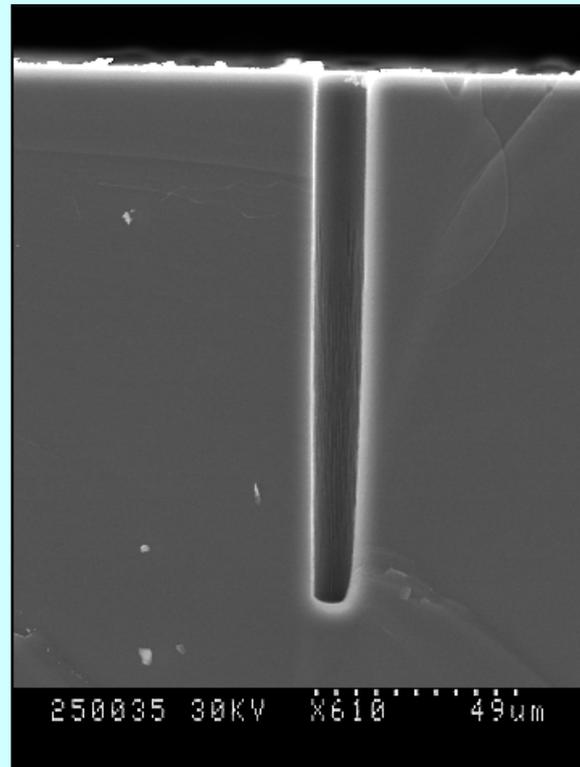
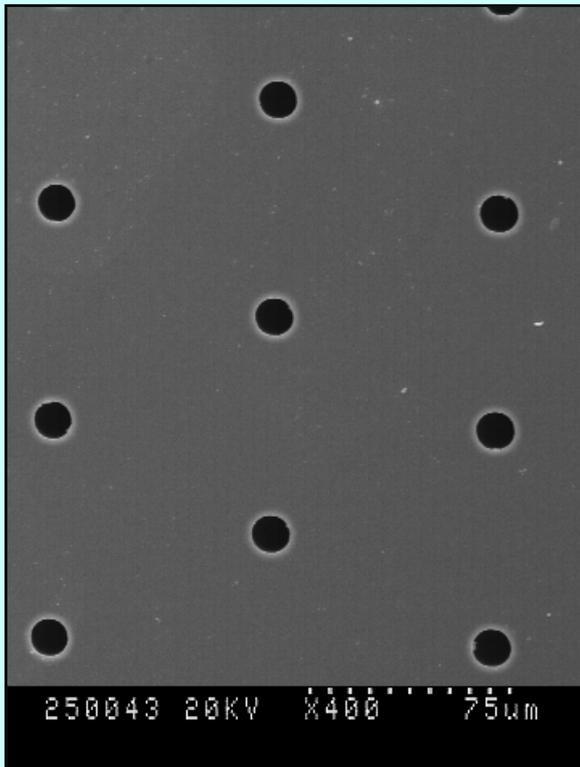
**Shottky-Schottky**  
**p-n junction**

● **Connection to the electronics**



**Wire bonding**  
**Bump bonding**

# Dry etching



Inductively Coupled Plasma

- **Mask:** photoresist
- **Gas:**  $\text{SF}_6$
- **Coating:**  $\text{C}_4\text{F}_8$
  
- **Diameter:**  $10 \mu\text{m}$
- **Spacing:**  $85 \mu\text{m}$
- **Depth:**  $130 \mu\text{m}$
- **Etch time:** 100 minutes

**Aspect ratio 13:1**

# Electrical contacts

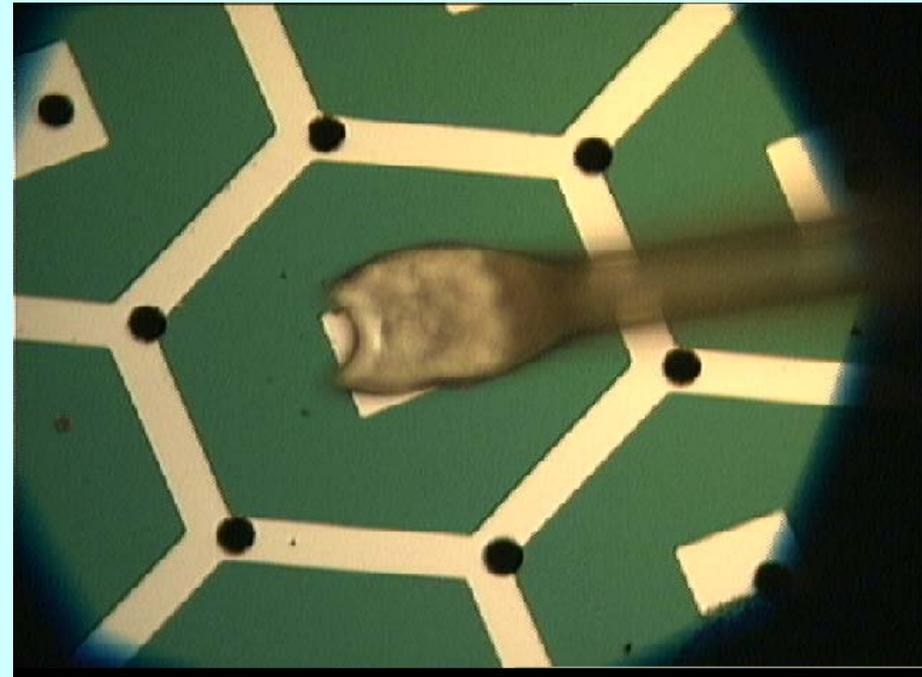
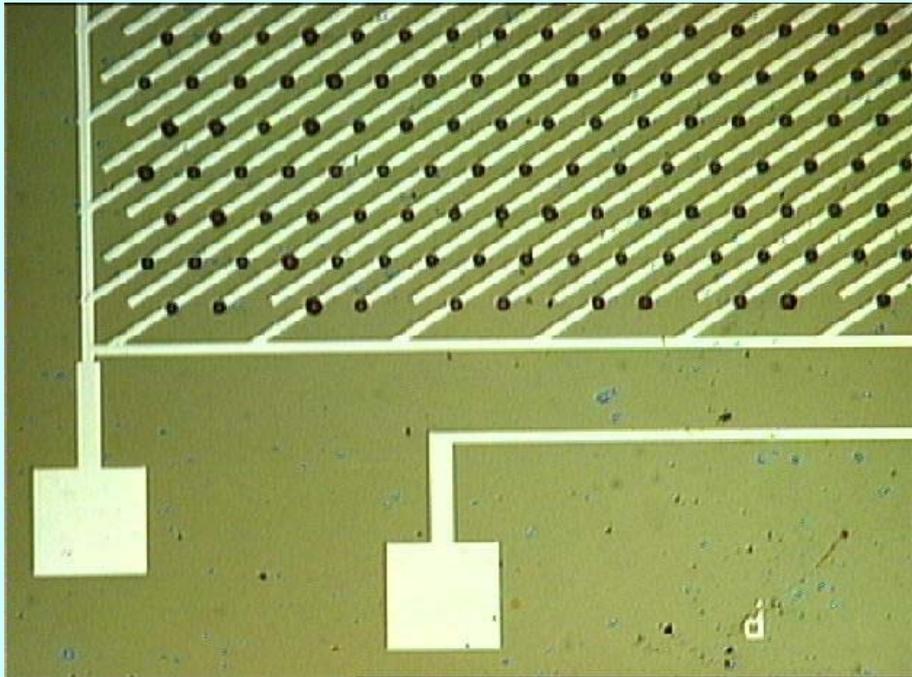


- **Metal evaporation:**

Ti (50 nm)  
Au (105 nm)

- **Tracks of Al (150 nm)**  
(over the SiO<sub>2</sub> layer)

- **Wire bonding**  
(25 μm wire)



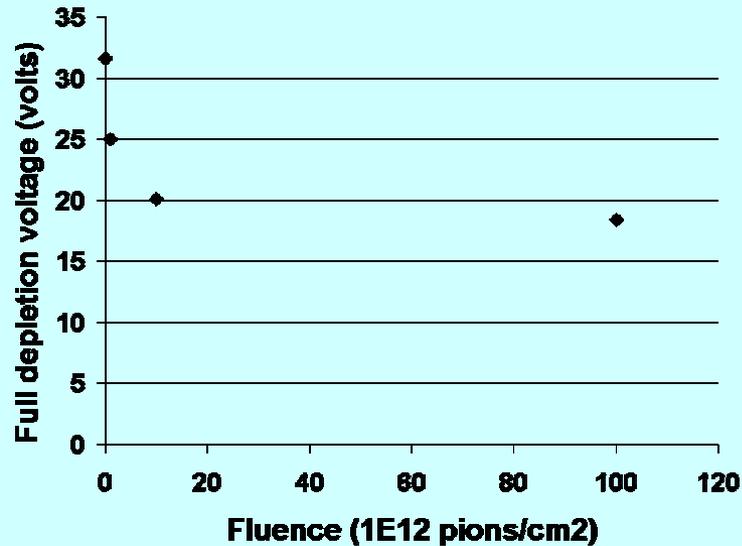
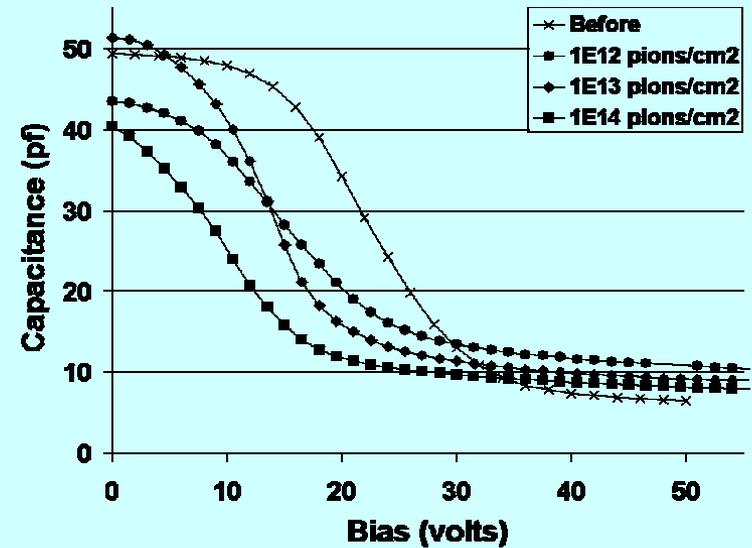
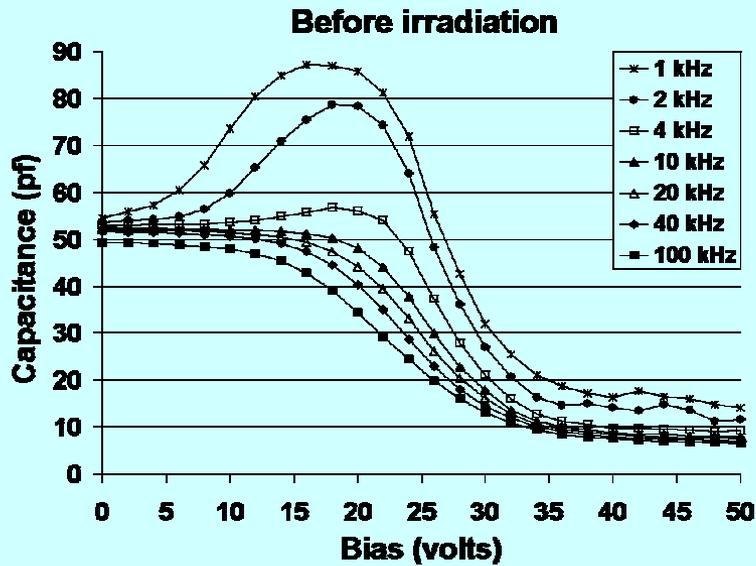
# Irradiation at PSI\*



- **Irradiation with 300 MeV/c  $\pi$  at PSI (Villigen)**
- **Bunch of 1 ns every 19 ns**
- **Flux of  $10^{14}$   $\pi/\text{cm}^2/\text{day}$**
- **3 fluences:  $10^{12}$ ,  $10^{13}$  and  $10^{14}$   $\pi/\text{cm}^2$**
- **4 low resistivity n-type silicon samples**

**\* Irradiation performed by K. Gabathuler, M. Glaser and M. Moll.**

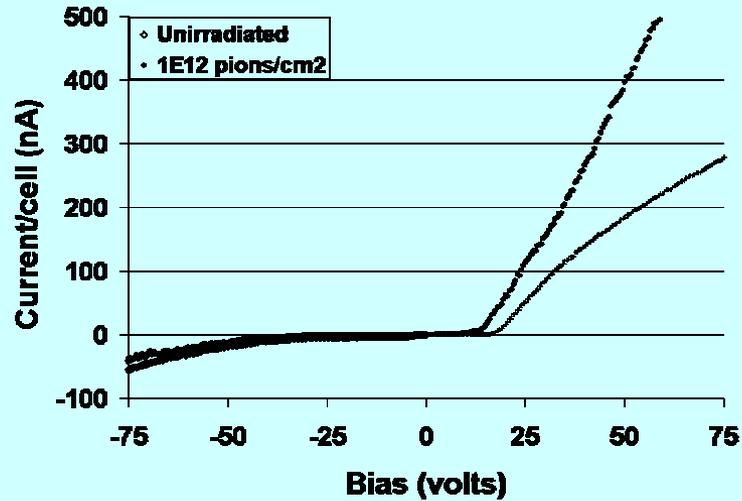
# Capacitance measurements (pions)



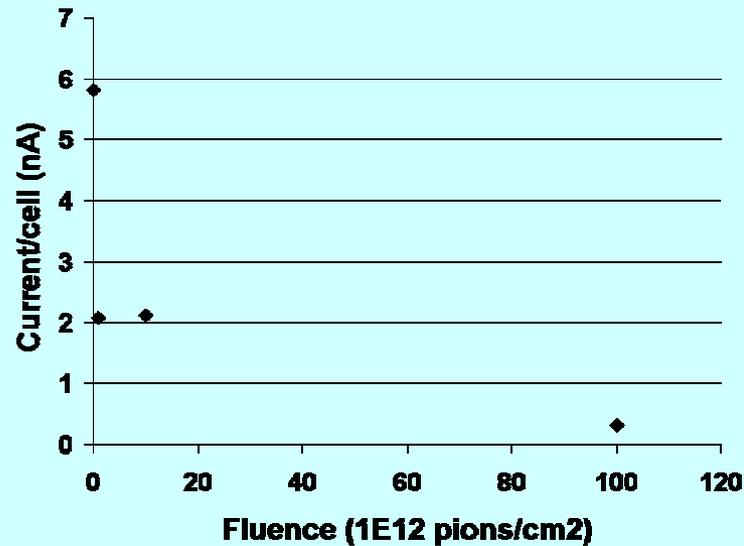
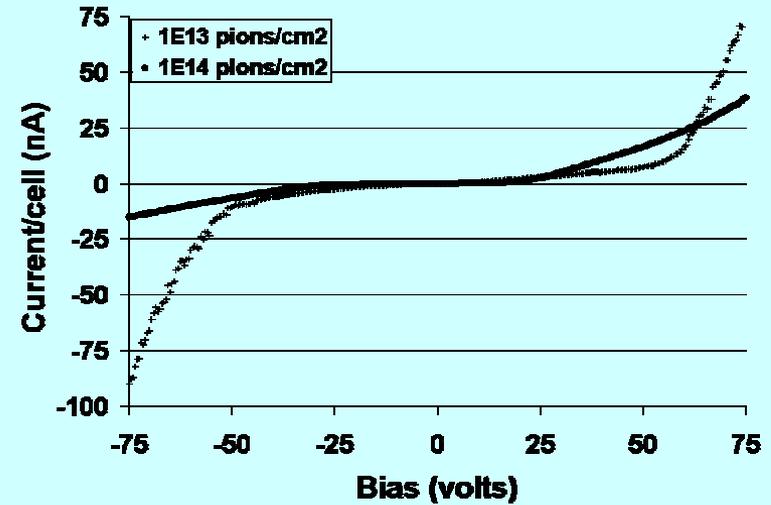
# Leakage current (pions)



I-V at low fluence



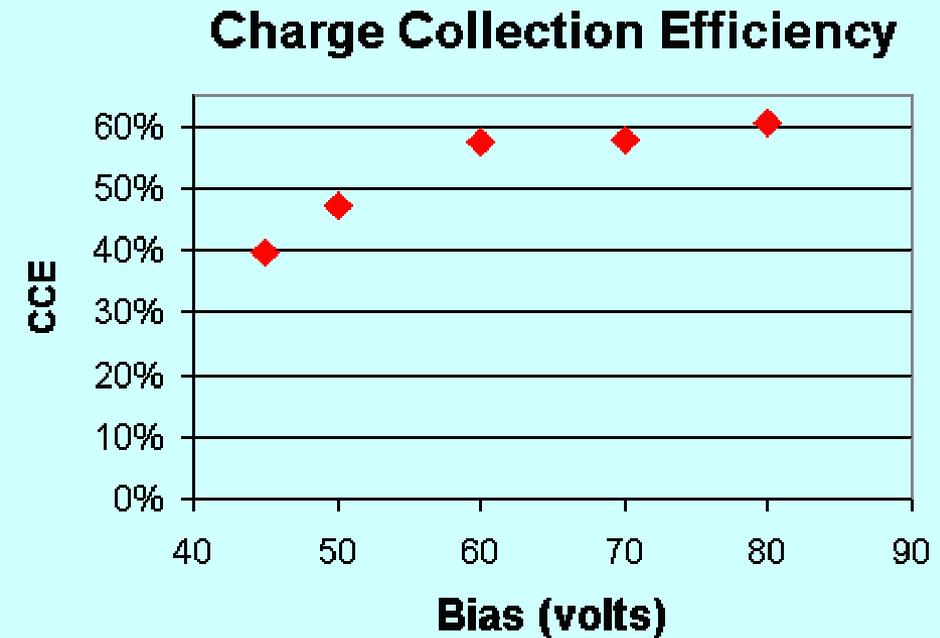
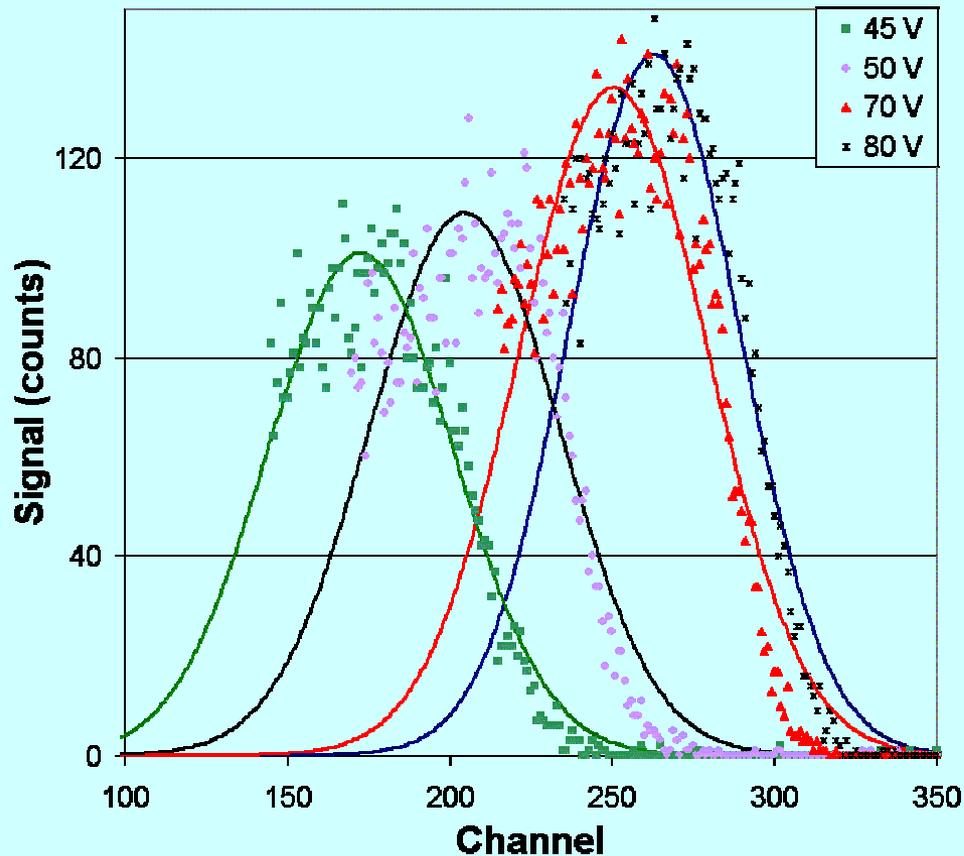
I-V at high fluence



# Alpha spectroscopy



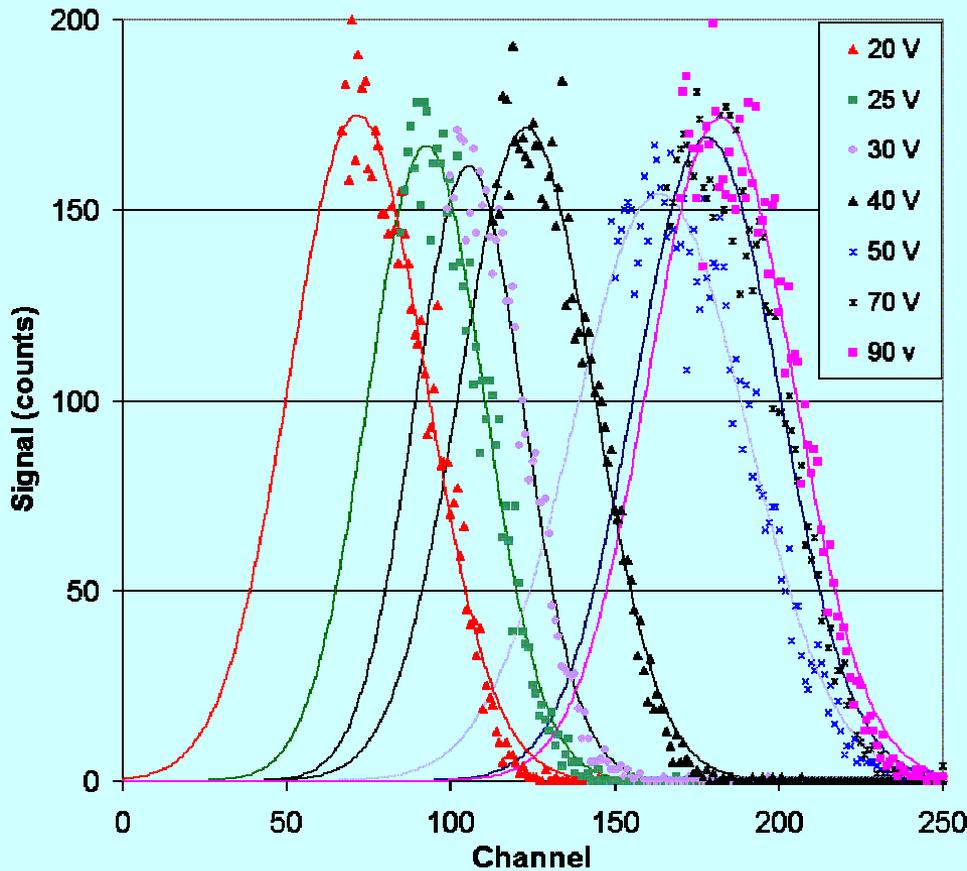
## 5.5 MeV alpha in Si before irradiation



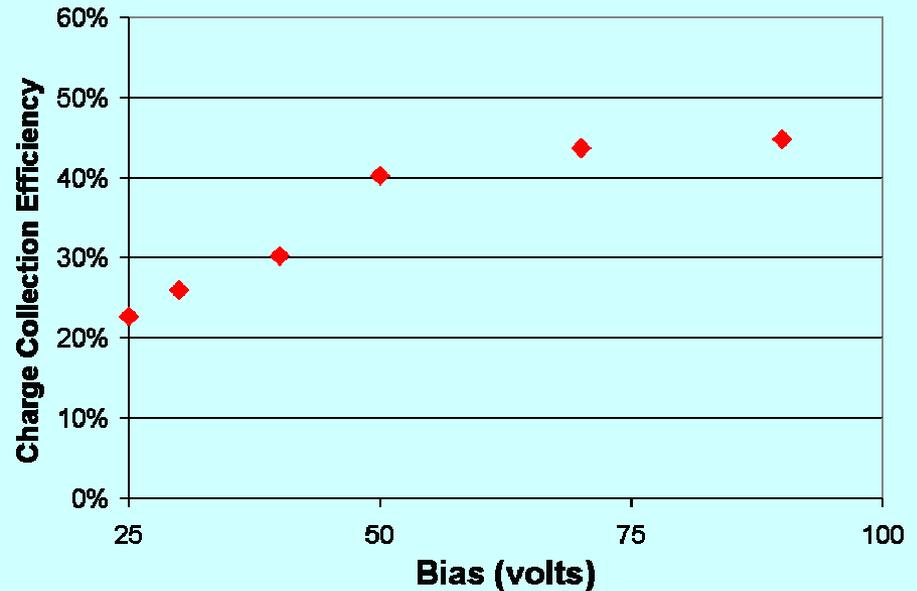
# Alpha spectroscopy (irradiated)



5.5 MeV alpha in Si after  $1E14$  pi/cm<sup>2</sup>



Charge Collection Efficiency



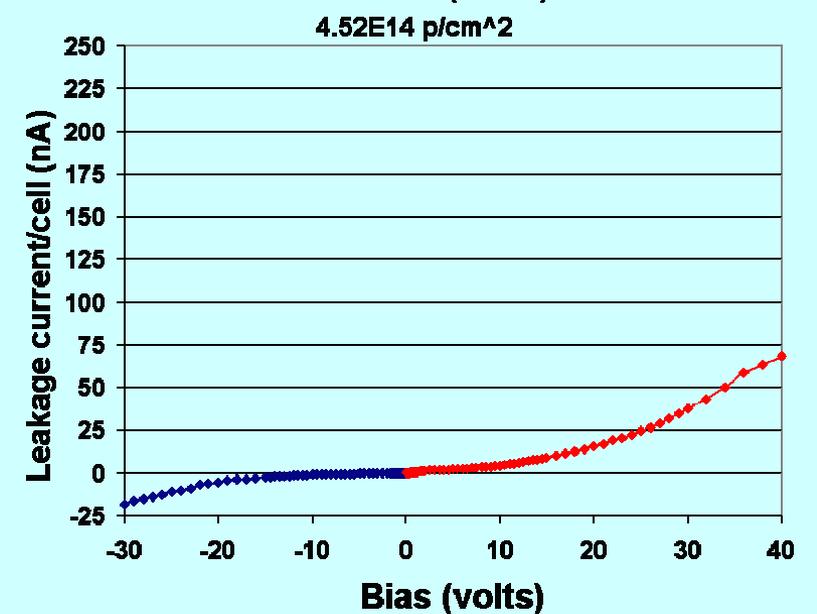
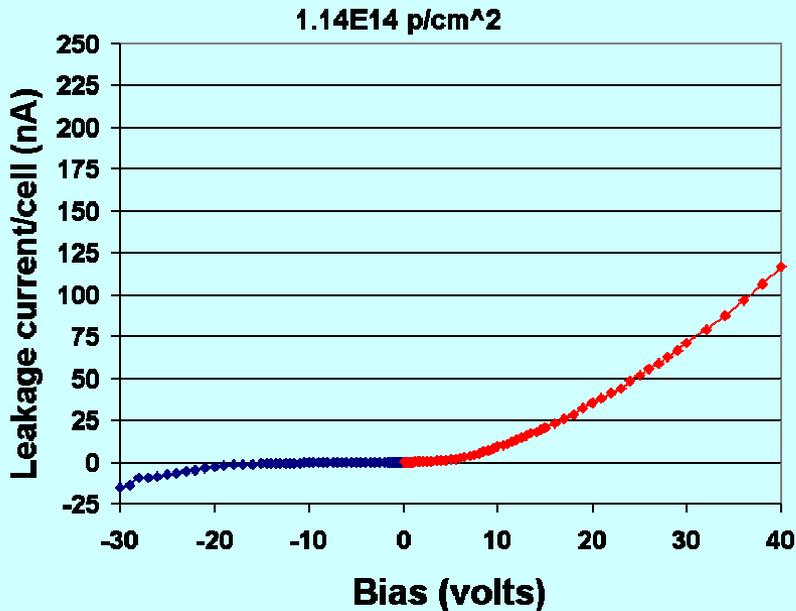
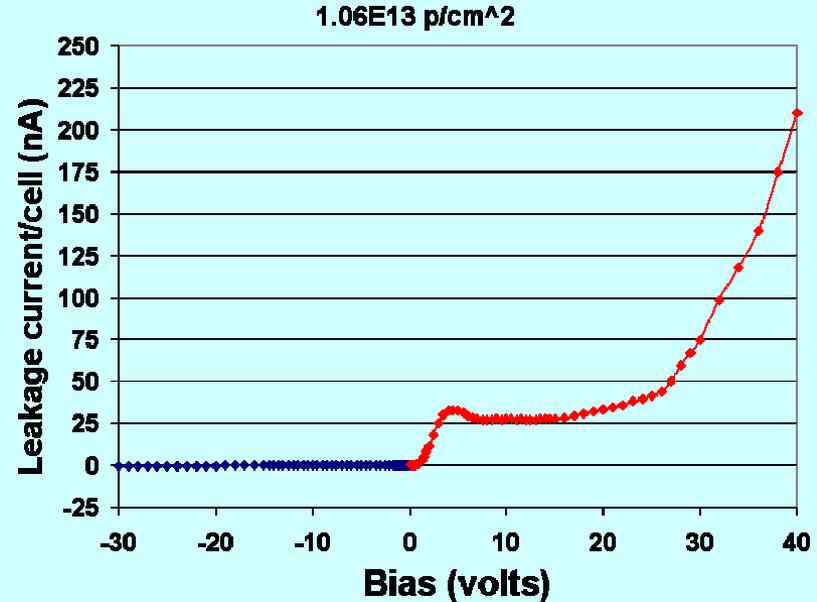
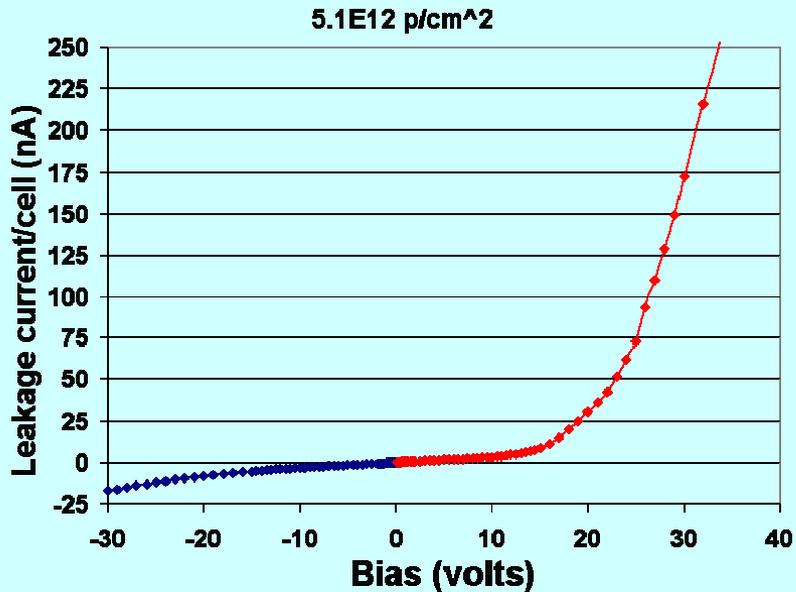
# Irradiation at CERN\*



- **Irradiation with 24 GeV/c protons at CERN**
- **Flux of  $1-3 \times 10^{13}$  p/cm<sup>2</sup>/h**
- **7 fluences between  $5 \times 10^{12}$  and  $5 \times 10^{14}$  p/cm<sup>2</sup>**
- **13 high resistivity n-type silicon samples**

**\* Irradiation performed by M. Glaser and M. Moll.**

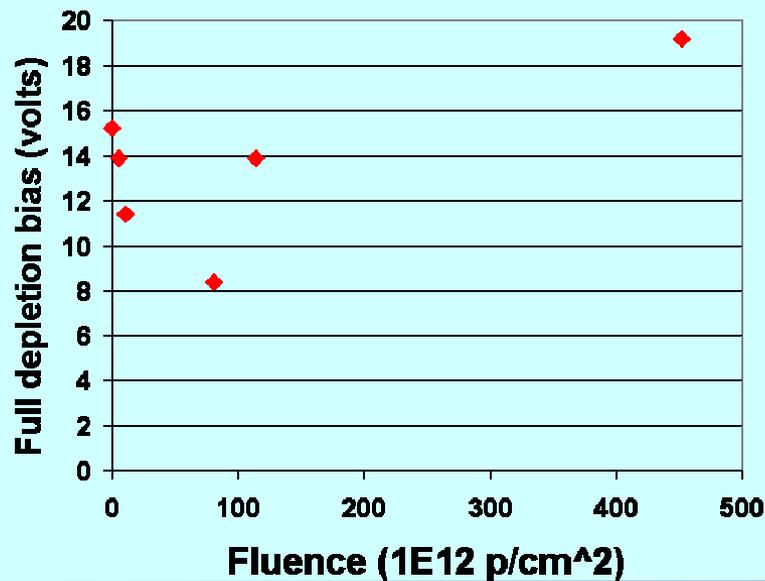
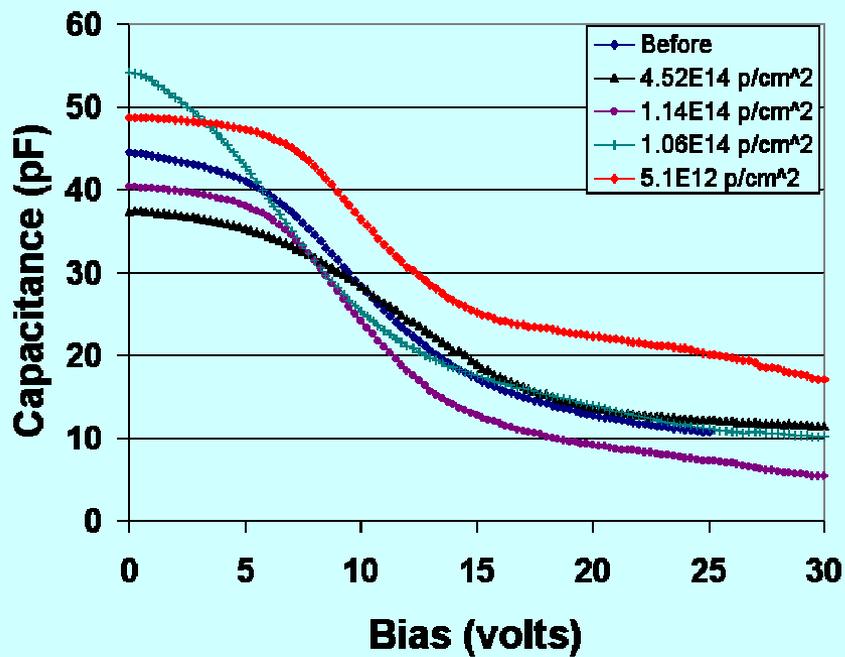
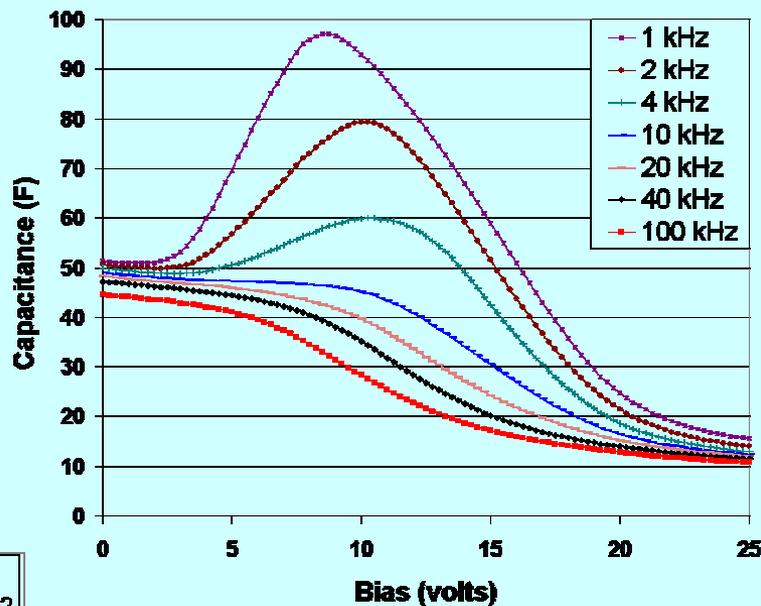
# Leakage current (protons)



# Capacitance measurements (protons)



Before irradiation



# In development



- **Improved aspect ratio of vias**
  - Dry etching ( $\sim 30:1^*$ )
  - PhotoElectroChemical etching ( $>30:1^*$ )
- **Improved electrodes**
  - pn junction
- **Improved readout electronics**
  - MEDIPIX1\*
  - LHCb VELO
  - ATLAS SCT

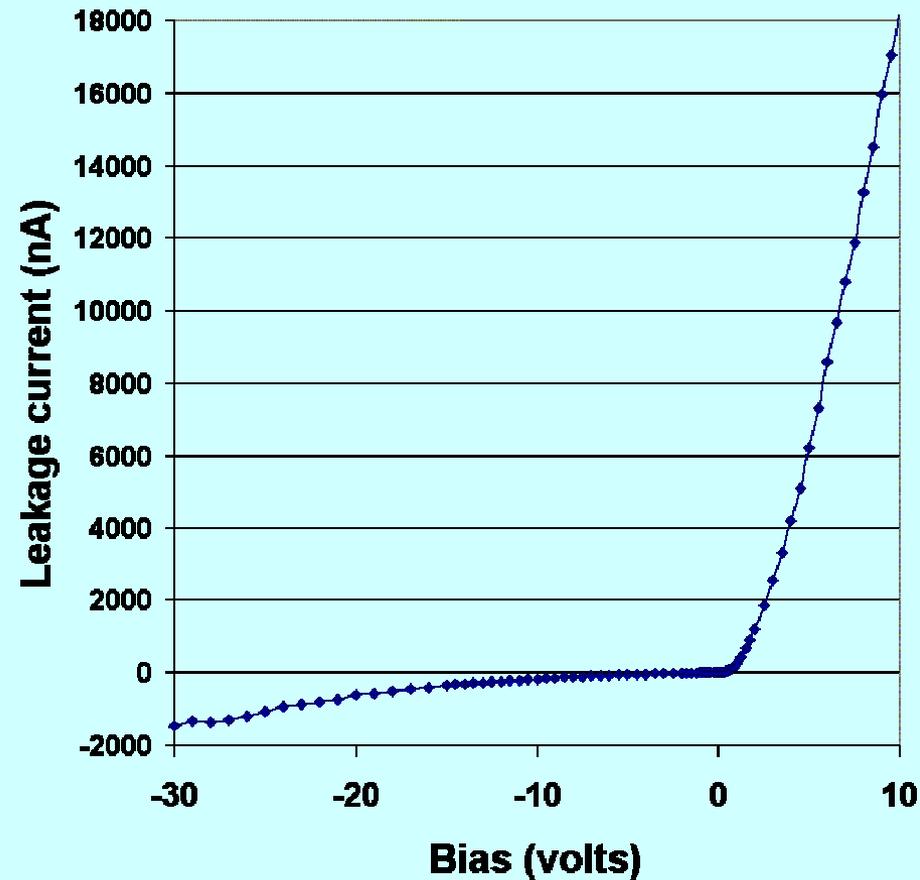
\* 3D-RID collaboration: [ppewww.ph.gla.ac.uk/3D-RID](http://ppewww.ph.gla.ac.uk/3D-RID)

# pn junction



## Sample's preparation:

- creation of central via
- boron doping
- creation of surrounding vias
- metal evaporation



# 3D MEDIPIX1\*

## MEDIPIX chip

-Pixels per chip

-64 x 64

-Pixel size

-170 x 170  $\mu\text{m}^2$

-Leakage current compensation

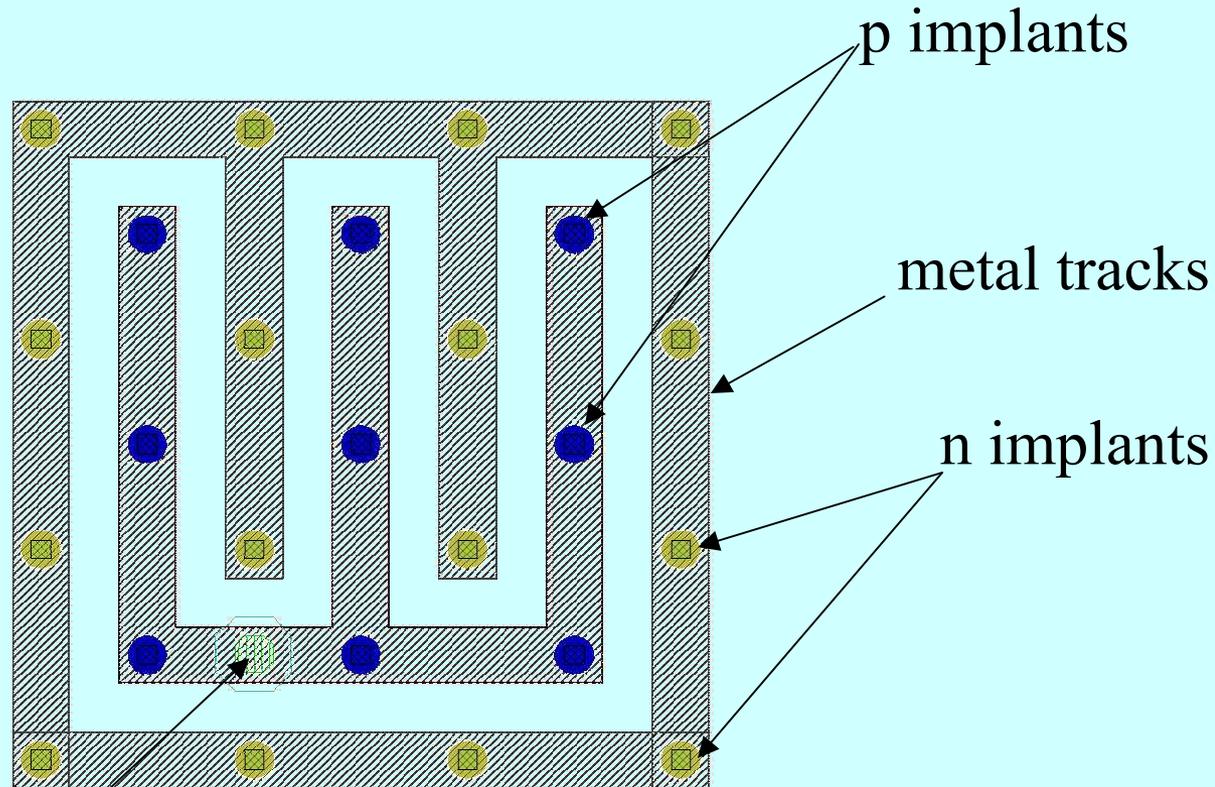
-Sensitive to positive input charge only

Vias diameter: 10  $\mu\text{m}$

Width of metal strips: 15  $\mu\text{m}$

Pitch: 56.67  $\mu\text{m}$

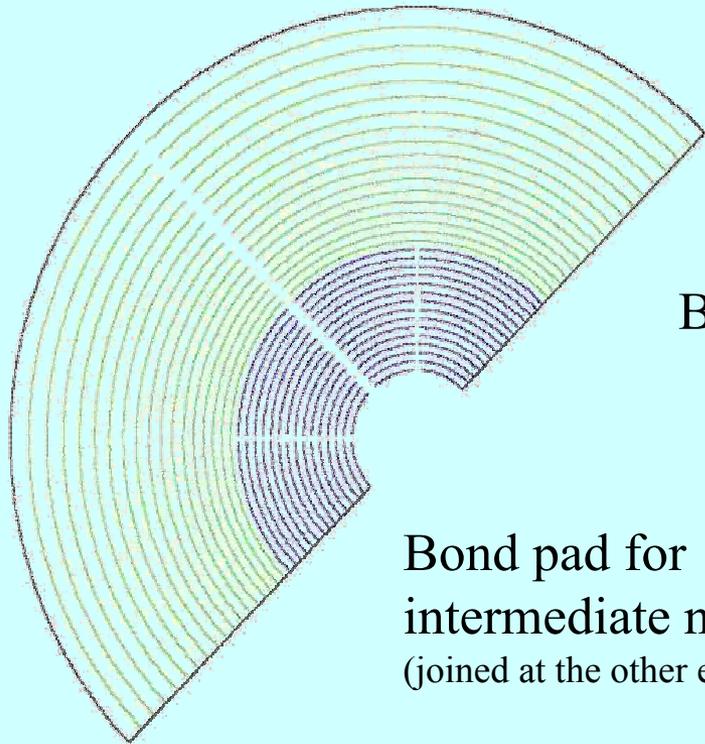
Cell pitch: 170.01  $\mu\text{m}$



position of "bump" consistent with MEDIPIX chip

\* 3D-RID collaboration: [ppewww.ph.gla.ac.uk/3D-RID](http://ppewww.ph.gla.ac.uk/3D-RID)

# LHCb - VELO\*

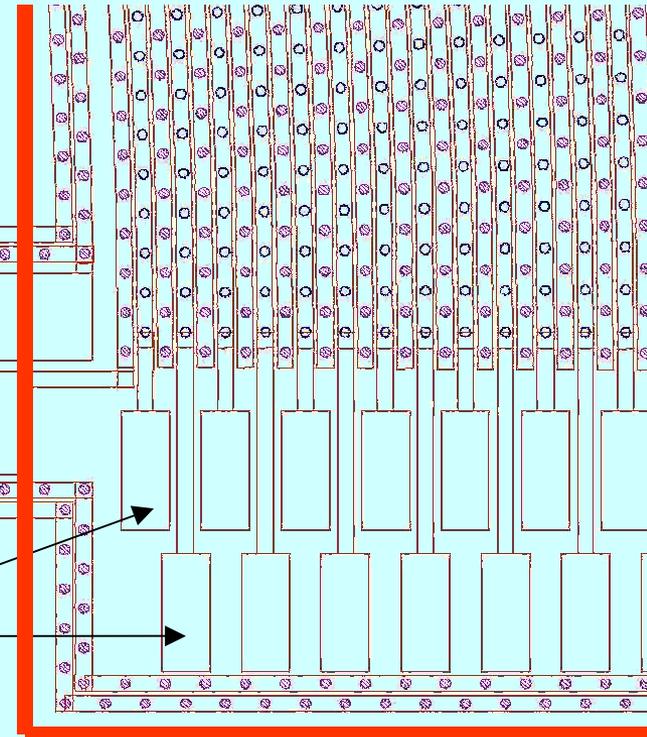


Constant via spacing of  $50\ \mu\text{m}$  along the strip.  
Via spacing varies with radius.

Bond pad for  
intermediate n-type strips  
(joined at the other end of the strips)

Bond pads for guard ring

Main bond pads  
(p-type strips)



Pitch varies linearly from  
 $45\ \mu\text{m}$  at the innermost  
region to  $90\ \mu\text{m}$  at strip 128

\* Designed in collaboration with C. Parkes

# ATLAS SCT

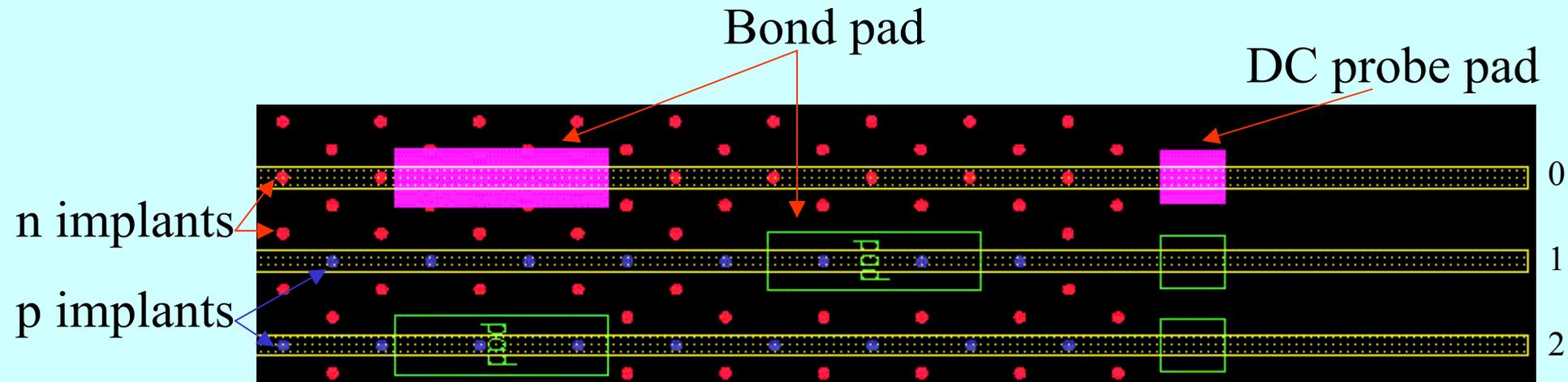


- Strip: 20  $\mu\text{m}$  x 1 cm  
80  $\mu\text{m}$  pitch

## Microstrips design (barrel)

- Small version ( $\sim 1 \text{ cm}^2$ )
- Channel: 128 + 2

- Hexagonal cells
- Vias: 10  $\mu\text{m}$  diameter  
53.3  $\mu\text{m}$  pitch



# Conclusion



- **Working 3D test structures**
- **Results from irradiation:**
  - Pions**
  - Protons**
- **In development:**
  - pn junctions**
  - proper readout electronics**

# Reminder



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[Database \(group leaders\)](#)

**WWW-Admin:**  
[Michael Moll](#)

## Irradiation Facilities

The following list contains irradiation facilities made available to members of the RD50 collaboration:

- [BNL](#) (Gamma 1.17 and 1.33 MeV)
- [CERN](#) (24 GeV/c protons, 1 MeV neutrons)
- [NCSR "Demokritos"](#) (Gamma, protons, neutrons)
- [Paul Scherrer Institut](#) (300 MeV/c pions)
- [Université catholique de Louvain](#) (Neutrons 1 to 70 MeV, Protons 10 to 75 MeV, Heavy Ions)
- [University of Karlsruhe](#) (26 MeV protons)
- [University of Ljubljana](#) (Neutrons)
- [Université de Montréal](#) (Protons up to 11 MeV, ions up to 5.5 MeV/charge)
- [Uppsala universitet](#) (Protons 500 keV to 10 MeV, ions 1 to 50 MeV)

*This list is maintained by the Glasgow group. Contact [Patrick Roy](#) for any updates/suggestions.*

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